

Capacitors **Multilayer Ceramic Chip Capacitors**

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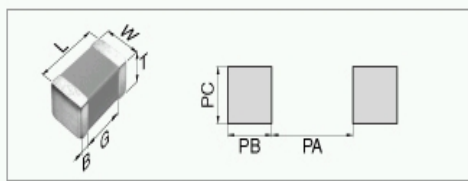
CGA5L4NP02W153J160AA Multilayer Ceramic Chip Capacitors

(TDK item description ? : CGA5L4NP02W153JT****)

Applications Automotive Grade

- Feature**
- Mid** Mid Voltage (100 to 630V)
 - 150°C** High Temperature Application
 - AEC-Q200** AEC-Q200

Series CGA5(3216) [EIA CC1206]

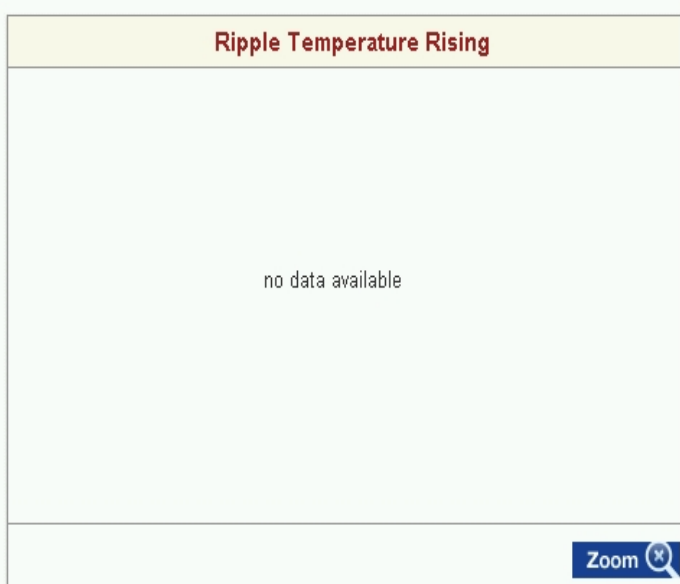
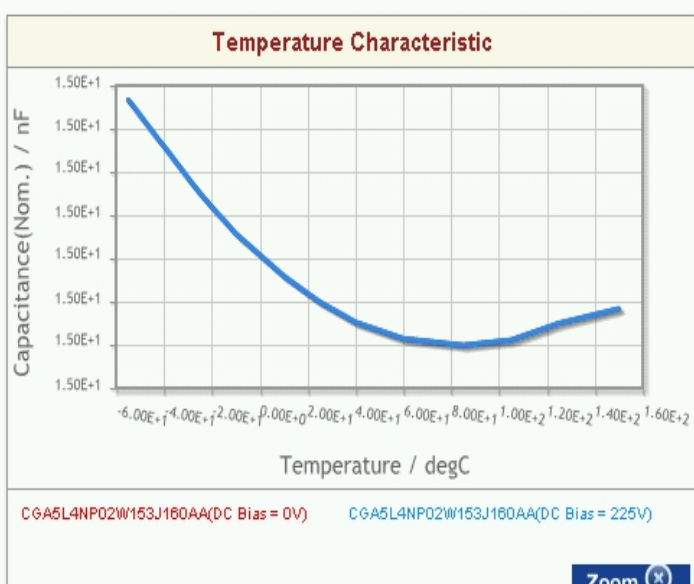
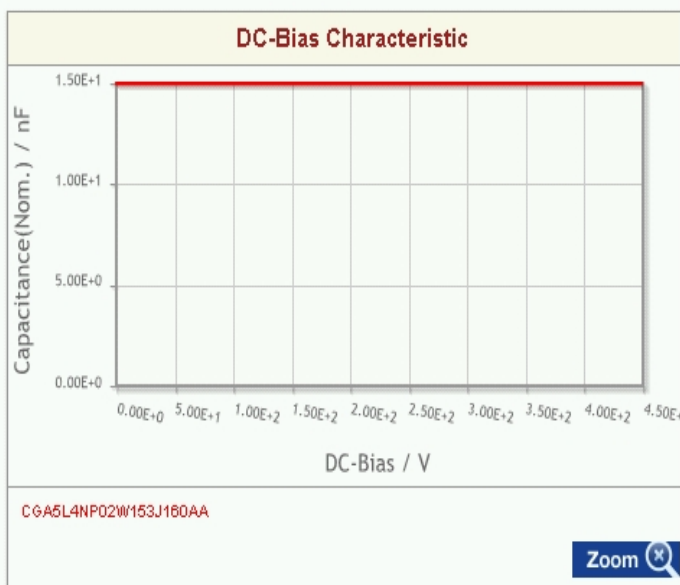


Size	
Length(L)	3.20mm +0.30/-0.10mm
Width(W)	1.60mm +0.30/-0.10mm
Thickness(T)	1.60mm +0.30/-0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	
Recommended Land Pattern(PA)	2.10 to 2.50mm (Flow Soldering) 2.00 to 2.40mm (Reflow Soldering)
Recommended Land Pattern(PB)	1.10 to 1.30mm (Flow Soldering) 1.00 to 1.20mm (Reflow Soldering)
Recommended Land Pattern(PC)	1.00 to 1.30mm (Flow Soldering) 1.10 to 1.60mm (Reflow Soldering)
Recommended Slit Pattern(SD)	

Electrical Characteristics	
Capacitance	15nF +/-5%
Rated Voltage	450Vdc
Temperature Characteristic	NPO(0+/-30ppm/degC)
Q	1000 Min.
Insulation Resistance	10000MΩ Min.

Other	
Soldering Method	Reflow, Flow
AEC Q200	Yes
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000Pcs Min.

Characteristic Graphs (This is reference data, and does not guarantee the product's characteristics.)



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